2SA1500

Silicon PNP epitaxial planar type

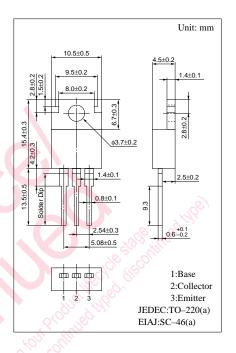
For power switching

Features

- High-speed switching
- ullet High collector to base voltage V_{CBO}
- Wide area of safe operation (ASO)
- Satisfactory linearity of foward current transfer ratio h_{FE}

Absolute Maximum Ratings (T_C=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to base voltage		V_{CBO}	-400	V	
Collector to emitter voltage		V_{CEO}	-400	V	
Emitter to base voltage		V_{EBO}	-7	V	
Peak collector current		I_{CP}	-8	A	
Collector current		I_C	-5	A	
Collector power	Γ _C =25°C	D	40	777	
dissipation	Ta=25°C	P_{C}	1.4	W	
Junction temperature		Tj	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



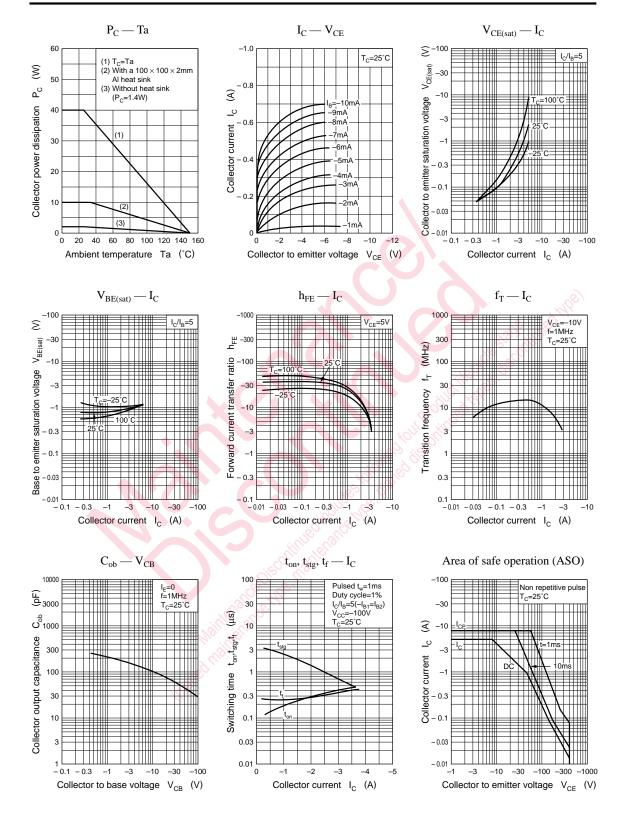
Electrical Characteristics (T_C=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = -400V, I_E = 0$			-100	μA
Emitter cutoff current	I_{EBO}	$V_{EB} = -7V, I_C = 0$			-100	μΑ
Collector to emitter voltage	V _{CEO}	$I_C = -10 \text{mA}, I_B = 0$	-400			V
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -5V, I_{C} = -0.5A$	20		100	
	h _{FE2}	$V_{CE} = -5V, I_{C} = -2A$	8			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = -2A, I_B = -0.4A$			-1.0	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = -2A, I_B = -0.4A$			-1.5	V
Transition frequency	f _T	$V_{CE} = -10V, I_{C} = -0.5A, f = 1MHz$		15		MHz
Turn-on time	ton	$I_C = -2A$,			1.0	μs
Storage time	t _{stg}	$I_{B1} = -0.4A, I_{B2} = 0.4A,$			2.5	μs
Fall time	$t_{\rm f}$	$V_{CC} = -100V$	·		1.0	μs

*h_{FE1} Rank classification

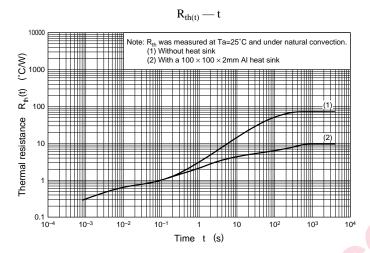
Rank	Q	P
h _{FE1}	20 to 60	50 to 100

Power Transistors 2SA1500



Panasonic 2

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